

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT2690081

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>TSUNG-HSUN LEE</td> <td>01/20/2014</td> </tr> <tr> <td>KAI-FA HO</td> <td>01/20/2014</td> </tr> </tbody> </table>		Name	Execution Date	TSUNG-HSUN LEE	01/20/2014	KAI-FA HO	01/20/2014						
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RECEIVING PARTY DATA													
<table border="1"> <tr> <td>Name:</td> <td>TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.</td> </tr> <tr> <td>Street Address:</td> <td>NO. 8, LI-HSIN RD. 6</td> </tr> <tr> <td>Internal Address:</td> <td>HSIN-CHU SCIENCE PARK</td> </tr> <tr> <td>City:</td> <td>HSIN-CHU</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77</td> </tr> </table>		Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.	Street Address:	NO. 8, LI-HSIN RD. 6	Internal Address:	HSIN-CHU SCIENCE PARK	City:	HSIN-CHU	State/Country:	TAIWAN	Postal Code:	300-77
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PROPERTY NUMBERS Total: 1													
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CORRESPONDENCE DATA													
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ATTORNEY DOCKET NUMBER:	TSMCP392US												
NAME OF SUBMITTER:	DAVID W. POTASHNIK												
Signature:	/David W. Potashnik/												

Date:

01/21/2014

Total Attachments: 4

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U.S. Patent Appln. No.
Filing Date

TSMC Docket No. TSMC2013-1137
Docket No. TSMCP392US

PATENT ASSIGNMENT

PARTIES TO THE ASSIGNMENT

Assignor(s):

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Taiwan (R.O.C.)

Assignor(s):

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Assignee:

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No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park
Hsin-Chu, Taiwan 300-77
Republic of China

AGREEMENT

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled

"WAFER OR RETICLE THERMAL DEFORMATION MEASURING TECHNIQUES"

for which:

a non-provisional application for United States Letters Patent:

☒ was executed on even date preparatory to filing (each inventor should sign this
Assignment on the same day as he/she signs the Declaration and Power of
Attorney); or

☐ was filed on _____ and accorded U.S. Serial No. _____; or

☐ I hereby authorize and request my attorney associated with Customer No.
107476, to insert on the designated lines below the filing date and application
number of said application when known:

U.S. Patent Appln. No.

Docket No. TSMCP392US

Filing Date

U.S. Serial No. _____,

filed on _____.

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

PATENT**REEL: 032007 FRAME: 0676**

U.S. Patent Appln. No.
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Docket No. TSMCP392US

✓ 104.01.20
Date

✓ Tsung - Hsun Lee
Name 1st Inventor Tsung-Hsun Lee

TSMC Docket No. TSMC2013-1137

Docket No. TSMCP392US

U.S. Patent Appln. No.

Filing Date

✓ 1/30
Date

✓ Kai Fa Ho
Name 2nd Inventor Kai-Fa Ho